



SOT323

plastic, surface-mounted package; 3 leads; 1.3 mm pitch; 2 mm x 1.25 mm x 0.95 mm body

29 July 2019

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	SC-70
Package type industry code	SC-70
Package style descriptive code	SOT (small outline transistor)
Package body material type	P (plastic)
JEITA package outline code	SC-70
Mounting method type	S (surface mount)
Issue date	16-03-2006
Manufacturer package code	SOT323

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.8	2	2.2	mm
package width	1.15	1.25	1.35	mm
seated height	0.8	0.95	1.1	mm
nominal pitch	-	1.3	-	mm
actual quantity of termination	-	3	-	



2 Package outline

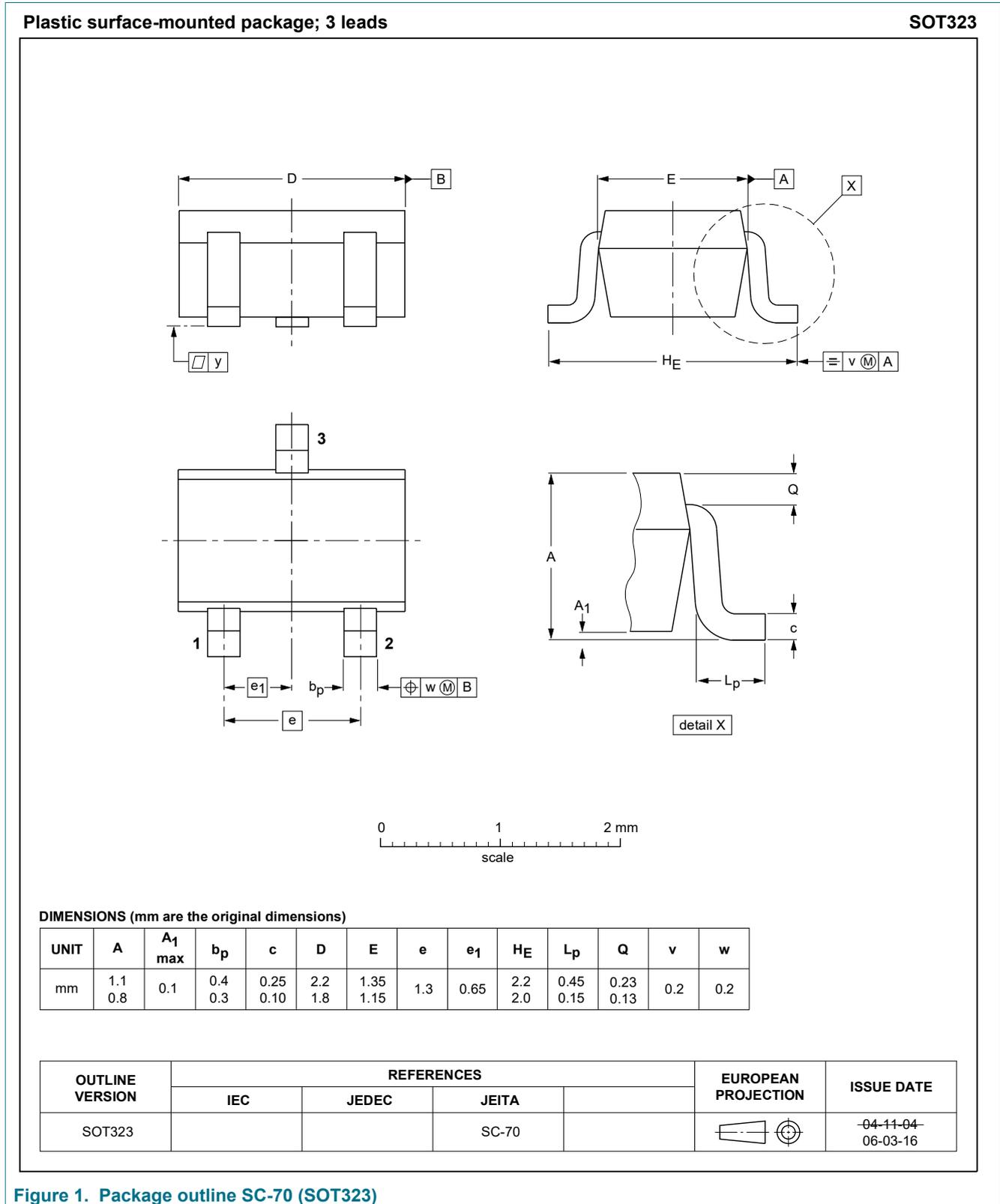
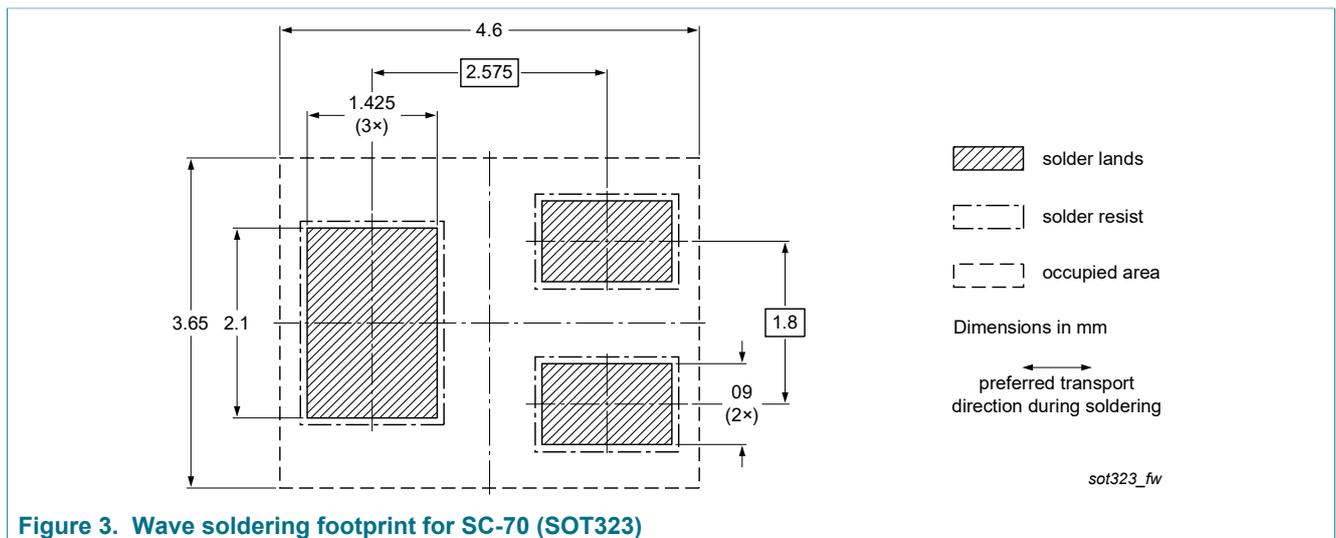
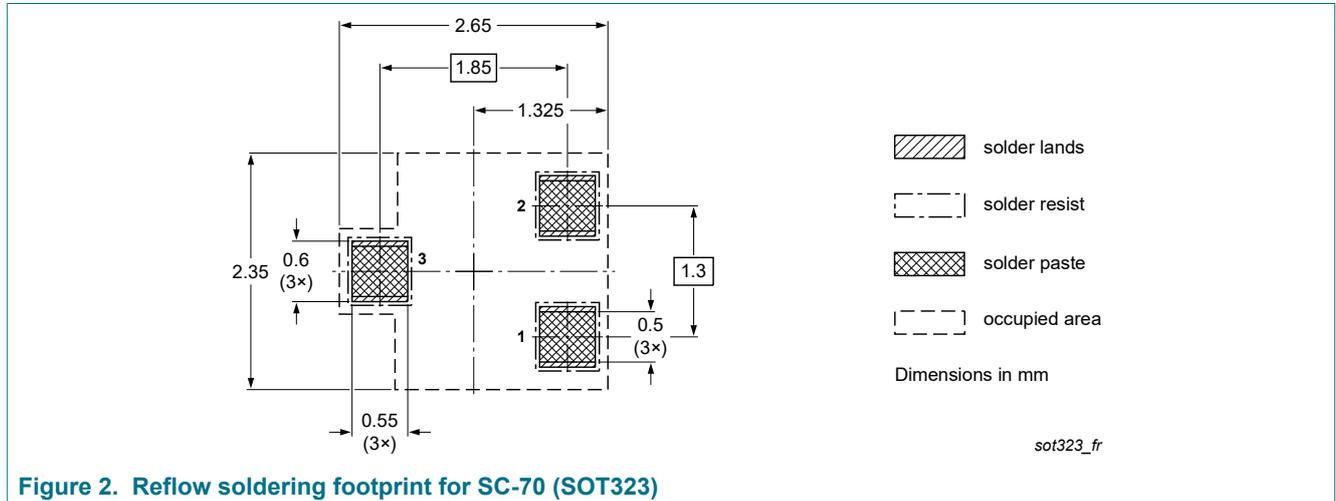


Figure 1. Package outline SC-70 (SOT323)

3 Soldering



4 Legal information

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